

6 Literatures

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6.2 Own publications

A. Journals

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2. Cai, D., Neyer, A., Kuckuk, R., Heise, H.M., „ Raman, infrared and visible spectroscopy of PDMS for characterization of polymer optical waveguide material”, in preparation
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B. Conference papers and posters

1. Cai, D., Neyer, A., „Realization of Electrical-Optical-Circuit-Board self-packaging,” Proceedings on 57th Electronic Components and Technology Conference, ECTC 2007, Reno, Nevada, USA, 2007, pp. 1368-1374.
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